

Abstract

To encapsulate electronic modules in a manner which is substantially resistant to water diffusion yet is carried out 5 at moderate temperatures below 300°C, preferably below 150°C, the invention provides a process for forming a housing for electronic modules, in particular sensors, integrated

circuits and optoelectronic components;

comprising the steps of:

- 10 - providing a substrate (1), of which at least a first substrate side (1a) is to be encapsulated,
- providing a vapor-deposition glass source (20),
- arranging the first substrate side (1a) in such a manner with respect to the vapor-deposition glass source that the 15 first substrate side (1a) can be vapor-coated;
- vapor-coating the first substrate side with a glass layer (4).